

# MA3J142DG, MA3J142EG

Silicon epitaxial planar type

For switching circuits

■ Features

- Two isolated elements contained in one package, allowing high-density mounting

■ Absolute Maximum Ratings  $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	80	V
Maximum peak reverse voltage	$V_{RM}$	80	V
Forward current	Single	$I_F$	100
	Double		150
Peak forward current	Single	$I_{FM}$	225
	Double		340
Non-repetitive peak forward surge current *	Single	$I_{FSM}$	500
	Double		750
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

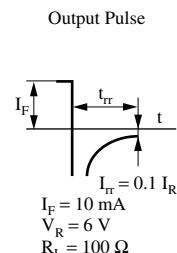
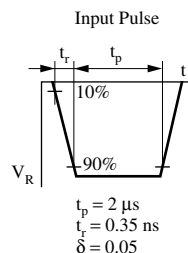
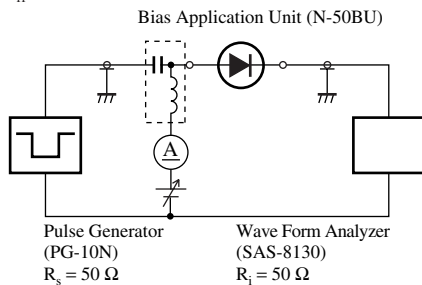
Note) \*:  $t = 1\text{ s}$

■ Electrical Characteristics  $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 100\text{ mA}$			1.2	V
Reverse voltage	$V_R$	$I_R = 100\ \mu\text{A}$	80			V
Reverse current	$I_R$	$V_R = 75\text{ V}$			100	nA
Terminal capacitance	MA3J142DG	$V_R = 0\text{ V}, f = 1\text{ MHz}$			15	pF
	MA3J142EG				2	
Reverse recovery time *	MA3J142DG	$I_F = 10\text{ mA}, V_R = 6\text{ V}$ $I_{rr} = 0.1 I_R, R_L = 100\ \Omega$			10	ns
	MA3J142EG				3	

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz.
3. \*:  $t_{rr}$  measurement circuit



■ Package

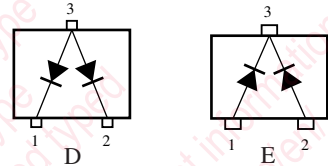
- Code: SMini3-F2
- Pin Name: MA3J142DG, MA3J142EG

- 1: Cathode 1, 1: Anode 1
- 2: Cathode 2, 2: Anode 2
- 3: Anode, 3: Cathode

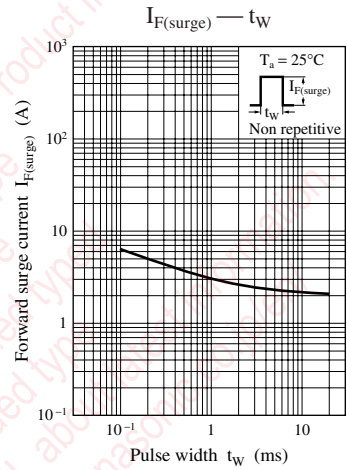
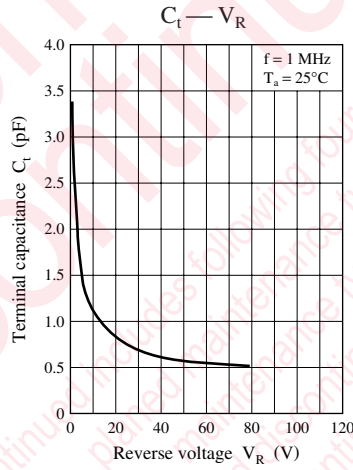
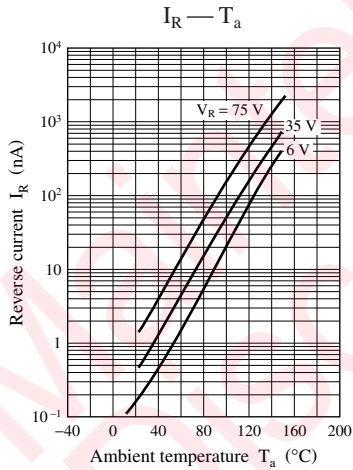
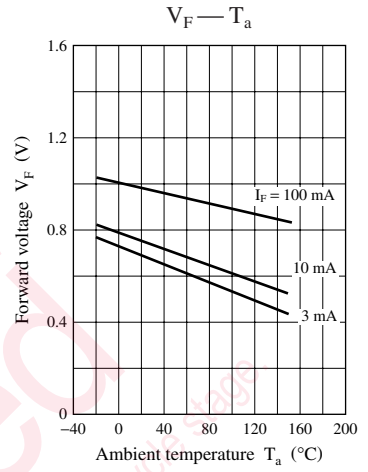
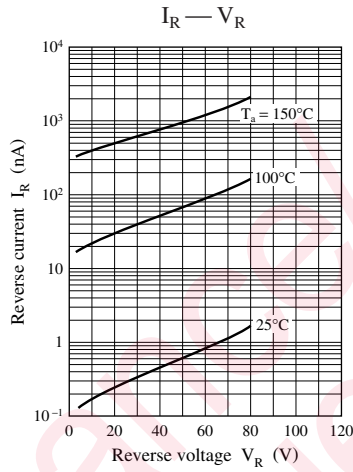
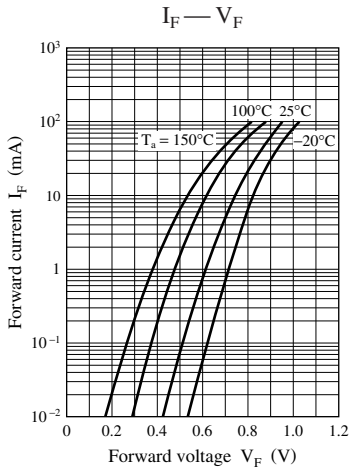
■ Marking Symbol

MA3J142DG: MO  
MA3J142EG: MU

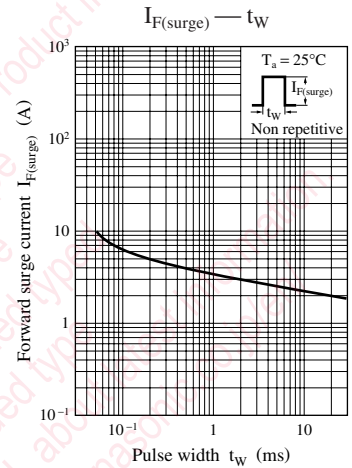
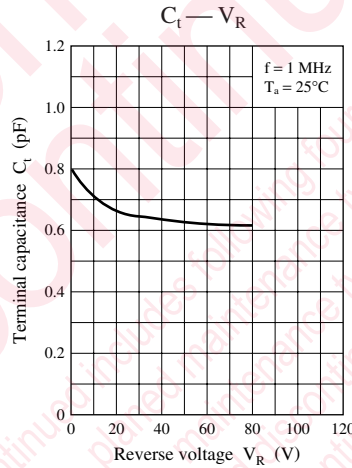
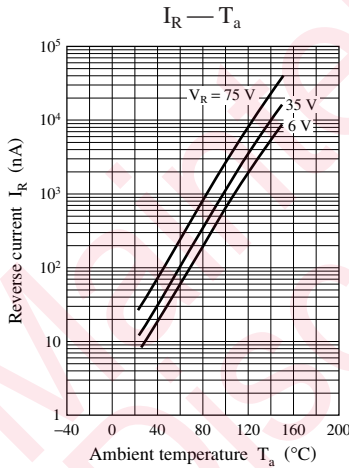
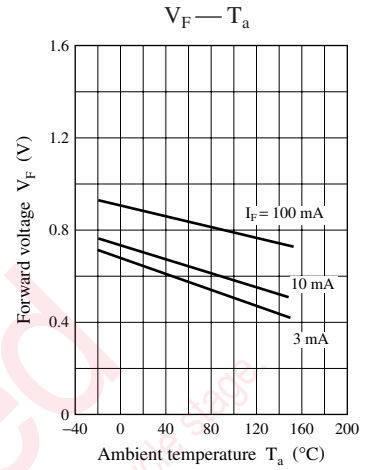
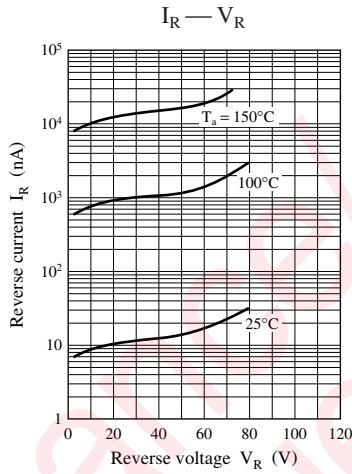
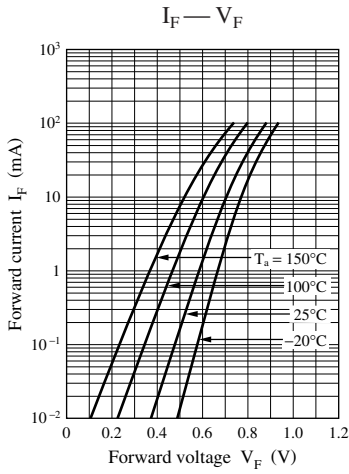
■ Internal Connection



Characteristics charts of MA3J142DG

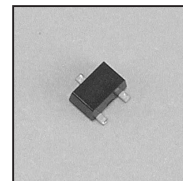
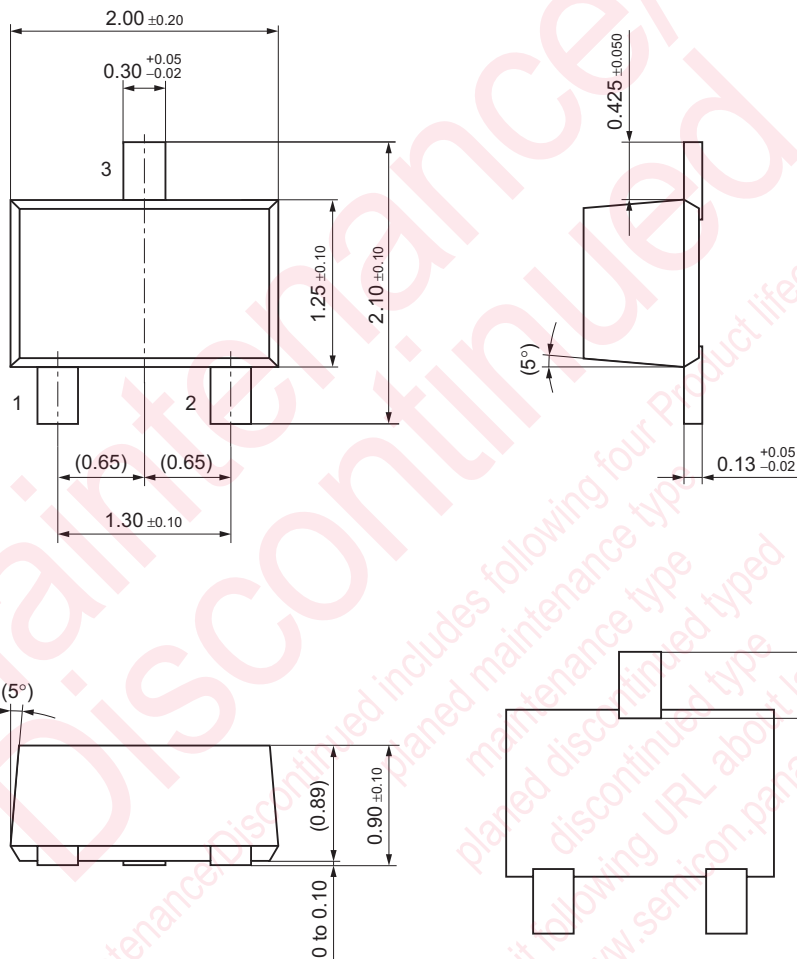


Characteristics charts of MA3J142EG



SMini3-F2

Unit: mm



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